



10/619039

2825

501.36127CC3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Yasushi KOUBUCHI, ET AL.

Serial No.: **10-619039**  
Rule 1.53(b) continuation of U.S. Patent Application  
Serial No.: 10/075,246, filed February 15, 2002

Filed: July 14, 2003

For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE, AND  
FABRICATION PROCESS AND DESIGNING METHOD  
THEREOF

Group of parent: 2825

Examiner of parent: Lee

**INFORMATION DISCLOSURE STATEMENT**  
**UNDER 37 CFR §1.97 AND §1.98**

RECEIVED  
AUG - 1 2003  
TC 2800 MAIL ROOM

Mail Stop DD  
Commissioner for Patents  
P.O. Box 1450  
Arlington, VA 22313-1450

July 30, 2003

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find a List of documents cited in prior application Serial No.: 10/075,246, filed February 15, 2002.

Since application Serial No. 10/075,246 is being cited under 35 U.S.C. §120 in the above-identified Continuation application, copies of the listed documents are not enclosed. See 37 CFR §1.98(d).

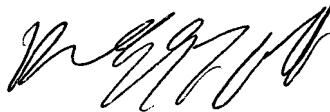
To the extent that the above-listed documents are not English, the requirements of 37 CFR §1.98(a)(3) are satisfied at least by the English translations enclosed with the documents as submitted in prior application Serial No.: 10/075 246

In view of all of the foregoing, consideration of the listed documents, upon examination of the above-identified application, is respectfully requested.

Kindly charge any additional fees due, or credit overpayment of fees, to Deposit Account No. 01-2135 (501.36127CC3).

Respectfully submitted,

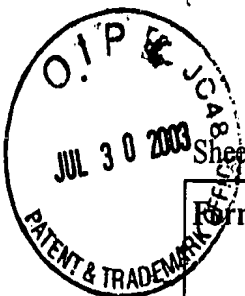
ANTONELLI, TERRY, STOUT & KRAUS, LLP



Ralph T. Webb  
Registration No. 33,047

1300 North Seventeenth Street  
Suite 1800  
Arlington, VA 22209  
Tel.: 703-312-6600  
Fax.: 703-312-6666

RTW/dmw



Sheet 1 of 1

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTY. DKT. NO.  
501.36127CC2

SERIAL NO.

10/619039

INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT

(Use several sheets if necessary)

APPLICANT  
KOUBUCHI, et al.

FILING DATE  
July 10, 2003

GROUP  
2825

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AA	5,929,528	7-27-99	Kinugawa	257	776	
AB	5,621,241	4-15-97	Jain	257	632	
AC	5,892,277	4-6-99	Ikemizu, et al.	257	700	
AD	5,292,689	3-94	Cronin, et al.			
AE	6,130,139	10-10-00	Ukeda et al.			
AF	6,346,736	2-12-02	Ukeda et al.			
AG						
AH						
AI						
AJ						
AK						
AL						

RECEIVED  
AUG - 1 2003  
MAIL ROOM

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation / Abstract	
						Yes	No
AM	7-74175	3-17-95	Japan			X	
AN	07-092838	18-04-95	Japan			X	
AO	8314762	26-11-96	Japan			Corresponding USP '139	
AP	923844	6-2-97	Japan			Corresponding USP '736	
AQ							
AR							
AS							
AT							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AU	Lee, et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)", 1996, Symposium on VLSI Technology Digest of Technical Papers, pp. 158-159.
AV	
AW	
AX	
AY	
AZ	

Examiner

Date Considered